



Docket No. 57614 (71987)
[formerly 71987-10009]

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang et al.

U.S.S.N.: 09/916,021

GROUP: 2815

FILED: July 26, 2001

EXAMINER: C. Chu

FOR: SEMICONDUCTOR PACKAGE WITH HEAT SINK

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on this date October 15, 2002 in an envelope as "Express Mail Post Office to Addressee," mailing Label Number EL789782628US addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231.

By:

Maggie C. Hamelin
Maggie C. Hamelin

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated July 15, 2002 of the above-referenced application. A Request for Continued Examination (RCE) is submitted herewith. Please amend the application as follows:

IN THE CLAIMS

Please amend claims 1, 3, 10, 12, and 14 as follows:

1. (Amended) A semiconductor package with a heat sink, comprising:
a chip carrier;
at least one chip mounted on the chip carrier and electrically connected to the chip carrier;